

P-Ch 30V Fast Switching MOSFETs

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary



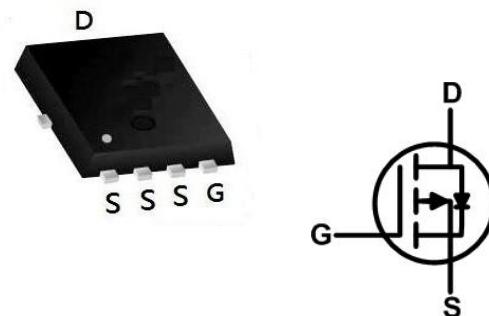
BVDSS	RDS(ON)	ID
-30V	10.3mΩ	-45A

Description

The XR45P03D is the high cell density trenched P-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The XR45P03D meet the RoHS and Gree Product requirement 100% EAS guaranteed with full function reliability approved.

PDFN3333-8L Pin Configuration

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current $T_C = 25^\circ\text{C}$	I_D	-45	A
		-23	
Pulsed Drain Current ¹	I_{DM}	-120	A
Single Pulse Avalanche Energy ²	EAS	45	mJ
Total Power Dissipation	P_D	29.7	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	$R_{\theta JA}$	78	°C/W
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	4.2	°C/W

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Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-30	-	-	V
Gate-body Leakage current	I_{GSS}	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$	-	-	± 100	nA
Zero Gate Voltage Drain Current T _J = 25°C T _J = 100°C	$I_{BS}\text{ss}$	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$	-	-	-1	μA
			-	-	-100	
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1.0	-1.6	-2.5	V
Drain-Source On-Resistance ⁴	$R_{DS(\text{on})}$	$V_{GS} = -10\text{V}, I_D = -15\text{A}$	-	10.3	13.5	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -10\text{A}$	-	15	20	
Forward Transconductance ⁴	g_{fs}	$V_{DS} = -10\text{V}, I_D = -15\text{A}$	-	15	-	S
Dynamic Characteristics⁵						
Input Capacitance	C_{iss}	$V_{DS} = -15\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	-	1405	-	pF
Output Capacitance	C_{oss}		-	177	-	
Reverse Transfer Capacitance	C_{rss}		-	147	-	
Gate Resistance	R_g	f=1.0MHz	-	11	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q_g	$V_{GS} = -10\text{V}, V_{DS} = -15\text{V}, I_D = -15\text{A}$	-	30	-	nC
Gate-Source Charge	Q_{gs}		-	5.5	-	
Gate-Drain Charge	Q_{gd}		-	8	-	
Turn-on Delay Time	$t_{d(on)}$	$V_{GS} = -10\text{V}, V_{DD} = -15\text{V}, R_G = 3\Omega, I_D = -15\text{A}$	-	10	-	ns
Rise Time	t_r		-	15	-	
Turn-off Delay Time	$t_{d(off)}$		-	110	-	
Fall Time	t_f		-	70	-	
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V_{SD}	$I_S = -1\text{A}, V_{GS} = 0\text{V}$	-	-	-1.2	V
Continuous Source Current	$T_C = 25^\circ\text{C}$	I_S	-	-	-45	A

Note :

1. Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})}=150^\circ\text{C}$.
2. The EAS data shows Max. rating . The test condition is $V_{DD} = -25\text{V}, V_{GS} = -10\text{V}, L = 0.1\text{mH}, I_{AS} = -30\text{A}$.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

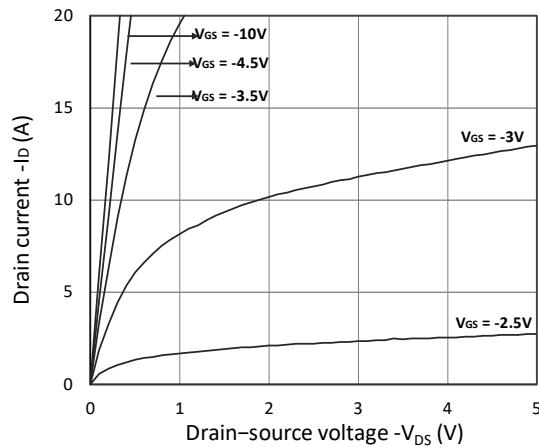


Figure 1. Output Characteristics

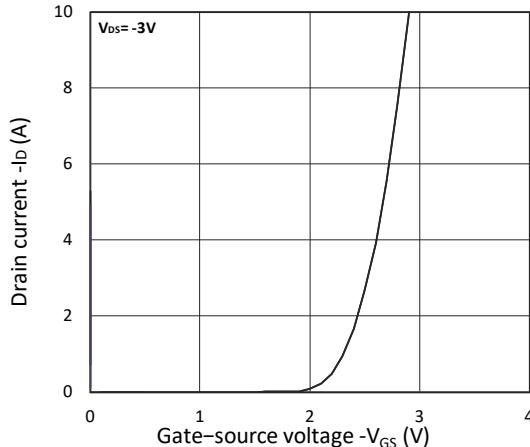


Figure 2. Transfer Characteristics

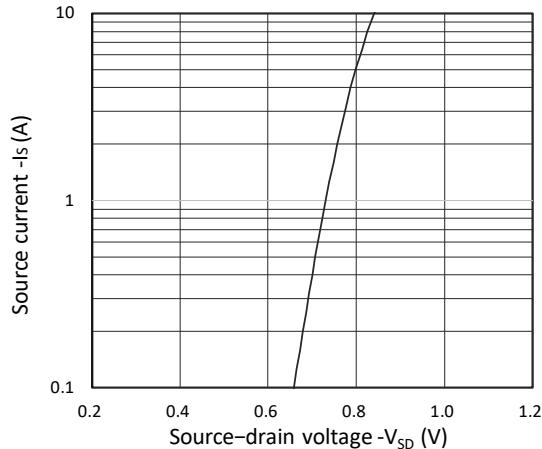


Figure 3. Forward Characteristics of Reverse

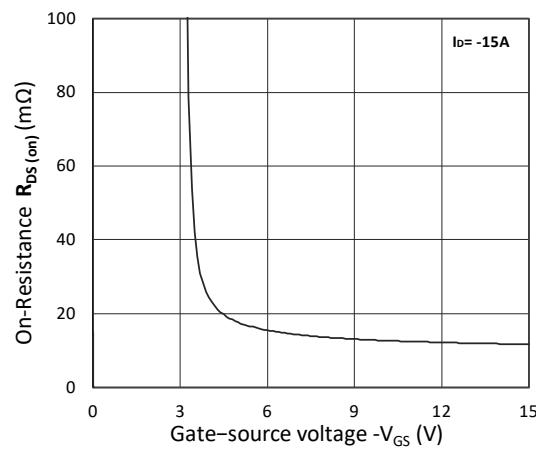


Figure 4. $R_{DS(on)}$ vs. V_{GS}

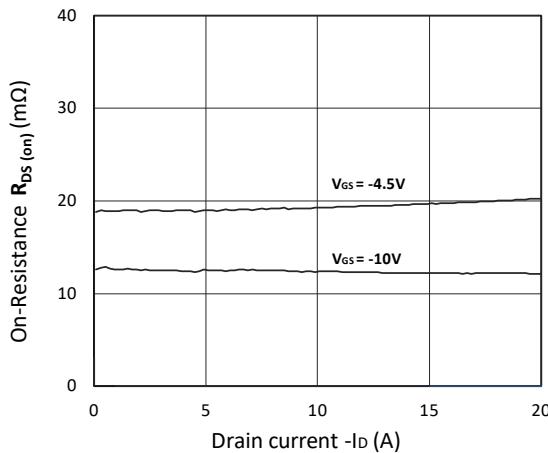


Figure 5. $R_{DS(on)}$ vs. I_D

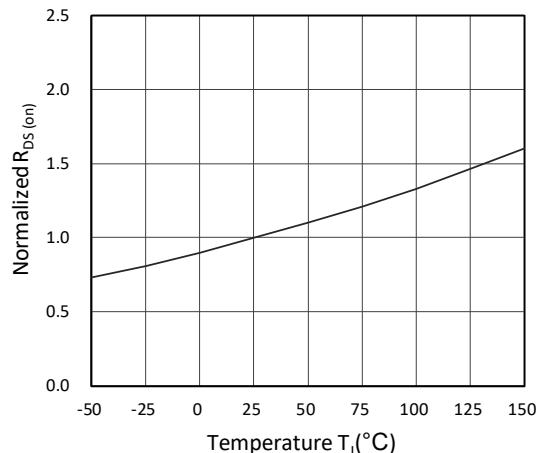


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

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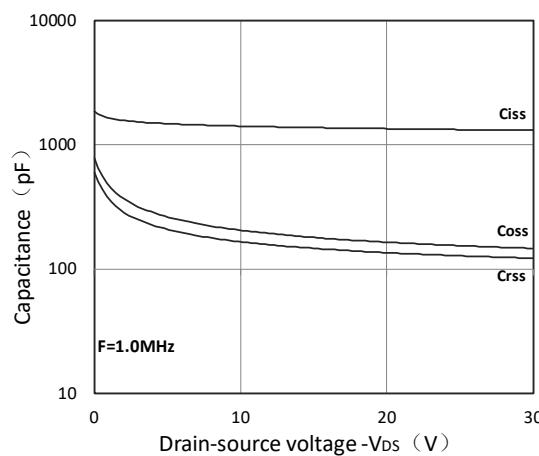


Figure 7. Capacitance Characteristics

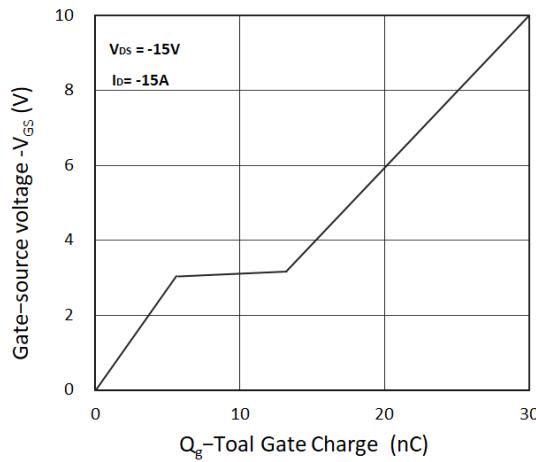


Figure 8. Gate Charge Characteristics

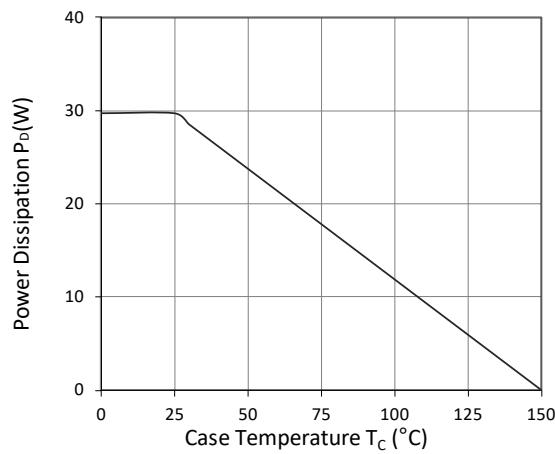


Figure 9. Power Dissipation

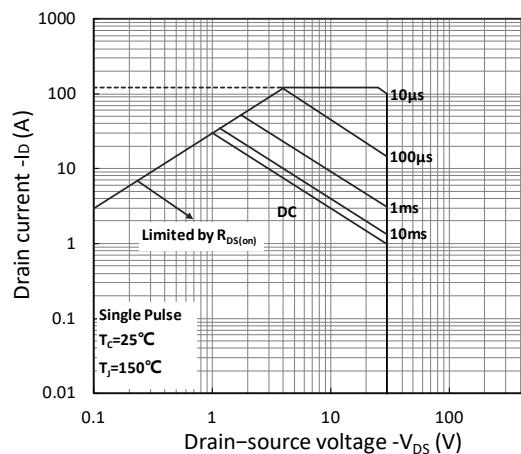


Figure 10. Safe Operating Area

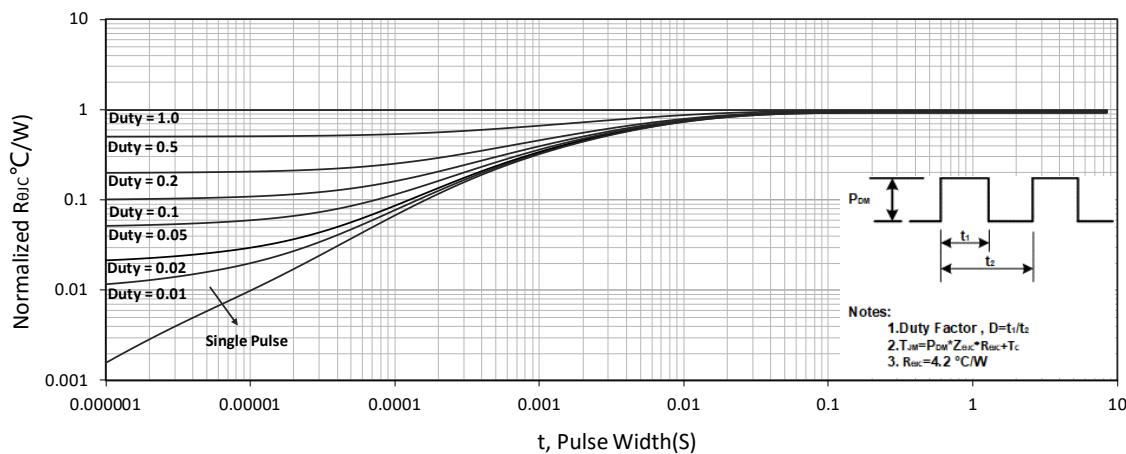


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

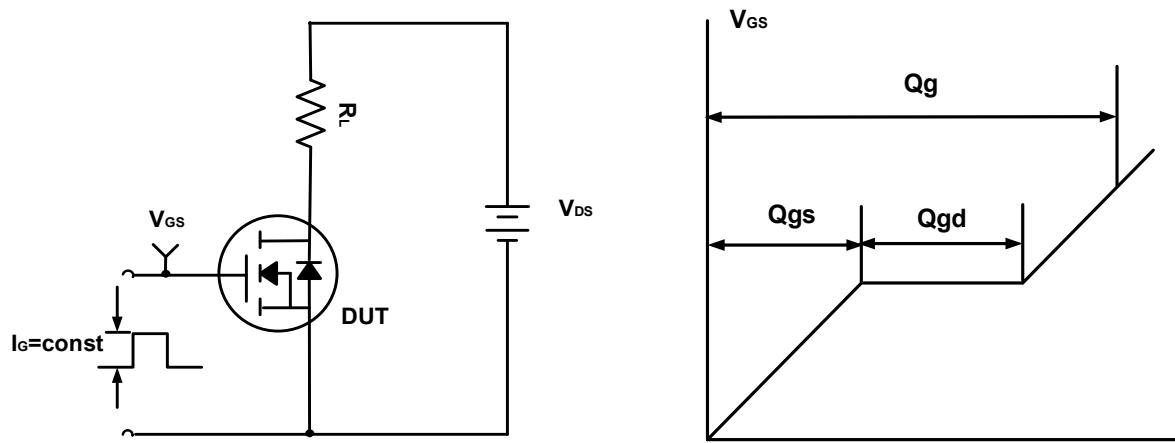


Figure A. Gate Charge Test Circuit & Waveforms

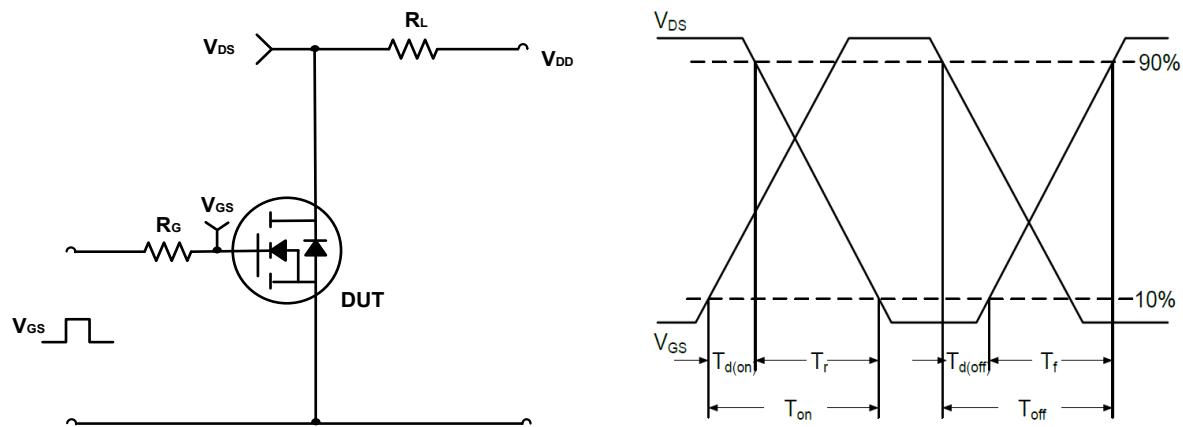


Figure B. Switching Test Circuit & Waveforms

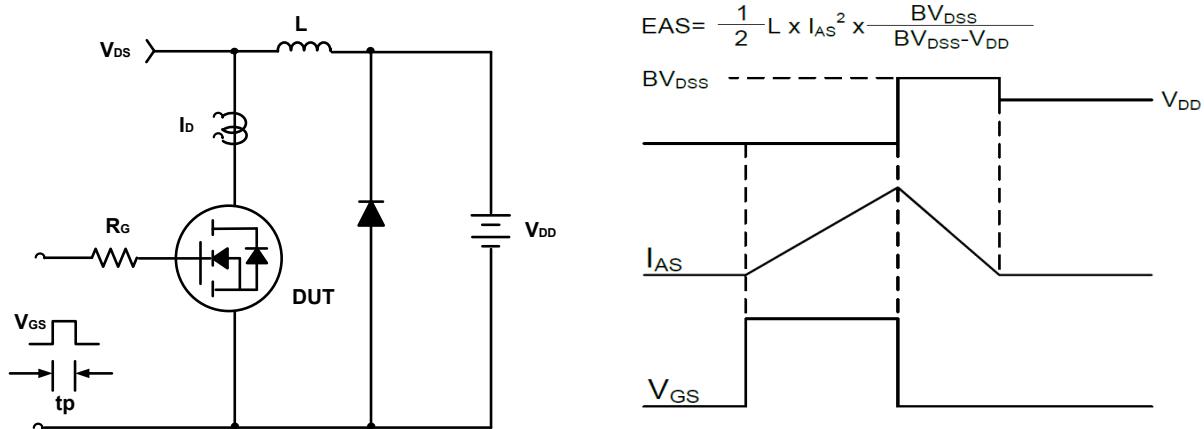
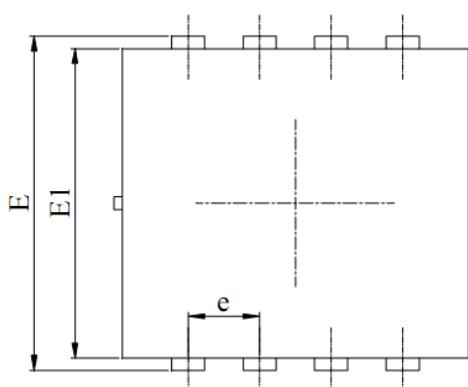
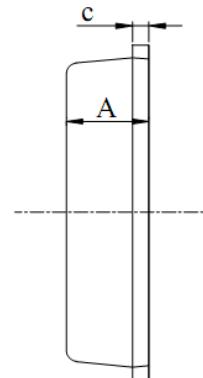


Figure C. Unclamped Inductive Switching Circuit & Waveforms

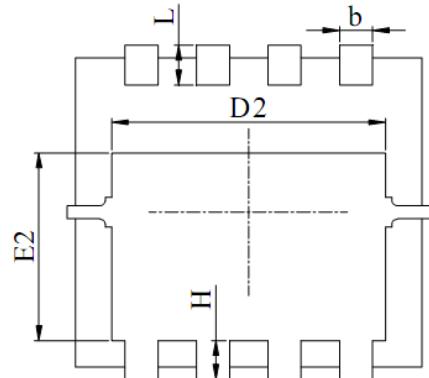
Package Mechanical Data-PDFN3333-8L-Single



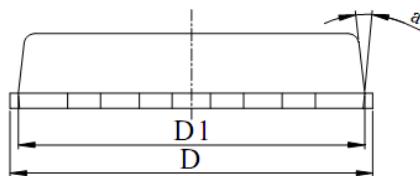
Top View



Side View



Bottom View

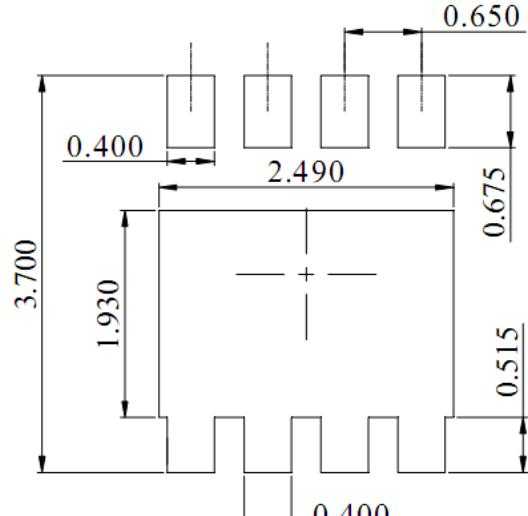


Front View

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M,1994.
2. ALL DIMNESIONS IN MILLIMETER (ANGLE IN DEGREE).
3. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

DIM.	MILLIMETER		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.20	0.25
D	3.00	3.15	3.25
D1	2.95	3.05	3.15
D2	2.39	2.49	2.59
E	3.20	3.30	3.40
E1	2.95	3.05	3.15
E2	1.70	1.80	1.90
e	0.65 BSC		
H	0.30	0.40	0.50
L	0.25	0.40	0.50
a	---	---	15°



DIMENSIONS:MILLIMETERS